

50. A method of underfilling a space between an electronic component and a carrier substrate the electronic component being mounted on the carrier substrate, comprising the steps of:

dispensing an amount of a curable one-part epoxy composition comprising:

(a) at least one epoxy compound which has two or more groups per soluble;

(b) a latent hardener component;

(c) a polythiol component; and

(d) at least one solid organic acid

substantially insoluble is a mixture of (a), (b) and (c) above, at room temperature within the range of about 15°C to 35°C and which remains substantially insoluble in effective amounts at temperatures below the activation temperature at which cure of the composition is initiated, into the space between the electronic component and the carrier substrate; and

exposing the composition to conditions which effect cure.

Kindly cancel Claims 1-32.

REMARKS


Applicants have cancelled Claims 1-32, and presented Claims 33-50 in their stead. These newly-presented claims

recite language defining the solid organic acid in a manner consistent with the parent application (No. 09/600,425), which has been allowed. Accordingly, Applicants request a prompt and favorable examination of these claims.

CONCLUSION

Applicants' undersigned attorney can be contacted by telephone at (860) 571-5001, by facsimile at (860) 571-5028 or by e-mail at steve.bauman@loctite.com. All correspondence should be directed to the address given below.

Respectfully submitted,



Steven C. Bauman
Attorney for Applicants
Registration No. 33,832

HENKEL LOCTITE CORPORATION
Legal Department
1001 Trout Brook Crossing
Rocky Hill, Connecticut 06067